

Yang

List of Publications by Year in descending order

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31
papers

237
citations

1163117

8
h-index

996975

15
g-index

31
all docs

31
docs citations

31
times ranked

186
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Wear Transitions in Particulate Reinforced Copper Matrix Composites. <i>Materials Transactions</i> , 2004, 45, 2332-2338. | 1.2 | 44 |
| 2 | Designing highly efficient 3D porous Ni-Fe sulfide nanosheets based catalyst for the overall water splitting through component regulation. <i>Journal of Colloid and Interface Science</i> , 2022, 616, 422-432. | 9.4 | 37 |
| 3 | The electrochemical corrosion behavior of Pb-free Sn-8.5Zn-XCr solders in 3.5wt.% NaCl solution. <i>Materials Chemistry and Physics</i> , 2015, 168, 27-34. | 4.0 | 25 |
| 4 | Enhancement of wear and corrosion resistance of low modulus β -type Zr-20Nb-xTi (x = 0, 3) dental alloys through thermal oxidation treatment. <i>Materials Science and Engineering C</i> , 2017, 76, 260-268. | 7.3 | 17 |
| 5 | Theoretical Prediction of Transition Metal Alloying Effects on the Lightweight TiAl Intermetallic. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2016, 47, 1451-1459. | 2.2 | 12 |
| 6 | Effect of Aluminum Addition on the Microstructure and Properties of Non-Eutectic Sn-20Bi Solder Alloys. <i>Materials</i> , 2019, 12, 1194. | 2.9 | 12 |
| 7 | Effect of graphene nano-sheets additions on the density, hardness, conductivity, and corrosion behavior of Sn-0.7Cu solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 202-211. | 2.2 | 12 |
| 8 | Microstructure optimization and mechanical properties of lightweight Al-Mg ₂ Si in-situ composite. <i>International Journal of Materials Research</i> , 2016, 107, 842-850. | 0.3 | 10 |
| 9 | Phase relationship in the Gd-Ti-Al ternary system at 500°C. <i>Journal of Materials Science</i> , 2002, 37, 1203-1205. | 3.7 | 9 |
| 10 | Influence of graphene nanosheets addition on the microstructure, wettability, and mechanical properties of Sn-0.7Cu solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 14035-14046. | 2.2 | 8 |
| 11 | Effect of addition of Al and Cu on the properties of Sn-20Bi solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 177-189. | 2.2 | 8 |
| 12 | Phase diagram of Er-Sn-Te system for diluted magnetic semiconductor developments. <i>Journal of Rare Earths</i> , 2013, 31, 800-803. | 4.8 | 7 |
| 13 | Phase Equilibria of the Al-Mo-Dy Ternary System at 873K. <i>Journal of Phase Equilibria and Diffusion</i> , 2013, 34, 322-327. | 1.4 | 5 |
| 14 | Particle size effect on the elevated temperature wear behavior of SiCp/Cu composites. <i>Journal of Materials Science</i> , 2005, 40, 223-225. | 3.7 | 4 |
| 15 | Phase Equilibria in the Al-Zr-Nd System at 773K. <i>Journal of Phase Equilibria and Diffusion</i> , 2011, 32, 24-29. | 1.4 | 4 |
| 16 | Phase equilibria of the Al-Cr-Pr ternary system at 773 K. <i>International Journal of Materials Research</i> , 2013, 104, 1233-1239. | 0.3 | 3 |
| 17 | Effect of Ni and TiO ₂ particle addition on the wettability and interfacial reaction of Sn20Bi lead-free solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 3306-3319. | 2.2 | 3 |
| 18 | Solid-State Phase Equilibria of the V-Si-Gd System at 973K (700°C). <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2014, 45, 4194-4200. | 2.2 | 2 |

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 19 | Experimental phase diagram of the Vâ€“Siâ€“Ho ternary system. International Journal of Materials Research, 2015, 106, 464-469. | 0.3 | 2 |
| 20 | Experimental Phase Diagram of the Alâ€“Moâ€“Gd Ternary System at 773ÅK. Journal of Phase Equilibria and Diffusion, 2015, 36, 218-223. | 1.4 | 2 |
| 21 | Solid-State Phase Equilibria and Intermetallic Compounds of the Si-V-Zr Ternary System. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2016, 47, 6569-6576. | 2.2 | 2 |
| 22 | Microstructure, Interface Morphology, and Antioxidant Properties of Sn-8.5Zn-0.1Cr-(Nd,Al,Cu) Solders. Journal of Electronic Materials, 2017, 46, 637-649. | 2.2 | 2 |
| 23 | Intrinsic Properties and Structure of AB ₂ Laves Phase ZrW ₂ . Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2017, 48, 3082-3089. | 2.2 | 2 |
| 24 | The effects of the addition of CNT@Ni on the hardness, density, wettability and mechanical properties of Sn-0.7Cu lead-free solder. Journal of Materials Science: Materials in Electronics, 2021, 32, 10843-10854. | 2.2 | 2 |
| 25 | Effects of Yttrium Addition on the Microstructure Evolution and Electrochemical Corrosion of SN-9Zn Lead-Free Solders Alloy. Materials, 2021, 14, 2549. | 2.9 | 2 |
| 26 | Phase equilibria in the Zrâ€“Siâ€“B ternary system (Zrâ€“Siâ€“ZrB ₂ region) at 1 173 K. International Journal of Materials Research, 2017, 108, 808-814. | 0.3 | 1 |
| 27 | Phase equilibria of the Cuâ€“Dyâ€“Ti ternary system at 973 K. Powder Diffraction, 2015, 30, 218-223. | 0.2 | 0 |
| 28 | The Effect of Indium Concentration on the Structure and Properties of Zirconium Based Intermetallics: First-Principles Calculations. Advances in Condensed Matter Physics, 2016, 2016, 1-8. | 1.1 | 0 |
| 29 | Phase equilibria of the Moâ€“Alâ€“Ho ternary system. International Journal of Materials Research, 2017, 108, 656-663. | 0.3 | 0 |
| 30 | Ternary Alâ€“Moâ€“Y phase diagram and the new phase Al ₄ Mo ₂ Y. International Journal of Materials Research, 2018, 109, 10-17. | 0.3 | 0 |
| 31 | The effect of alkaline earth additions on the physical property and the corrosion behavior of Sn-0.7Cu-0.075Al solder alloy. Journal of Materials Science: Materials in Electronics, 2021, 32, 24152-24167. | 2.2 | 0 |